

**METHOD FOR SEALING A SEMICONDUCTOR DEVICE AND APPARATUS
EMBODYING THE METHOD**

ABSTRACT

An apparatus includes a device chip having circuit elements fabricated on a substrate and a cap covering at least a portion of the device chip including the circuit elements such as thin film resonators. The placement of the cap on the device chip is sealed using a gasket having treaded surface for improved adhesion, cold weld deformation of gold, and decreased susceptibility to foreign particles resulting in a superior seal.